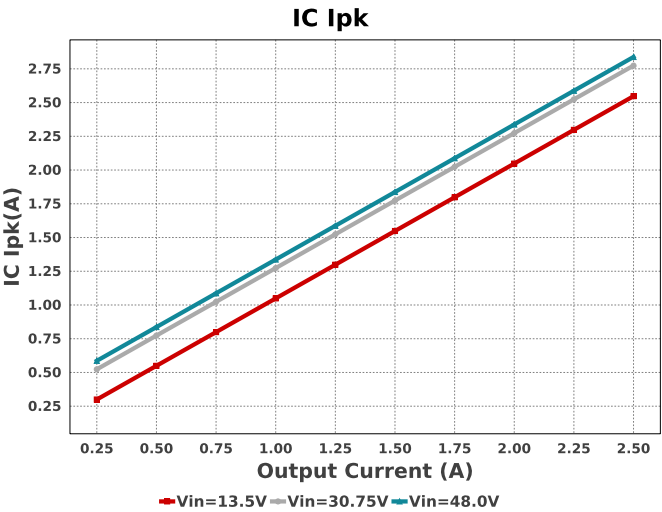
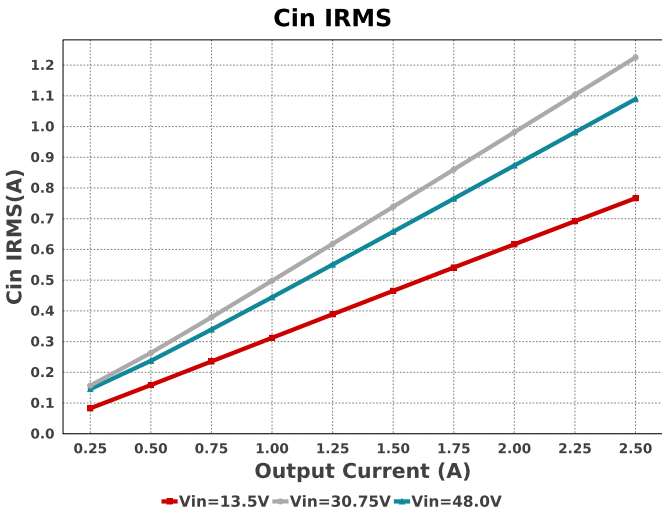
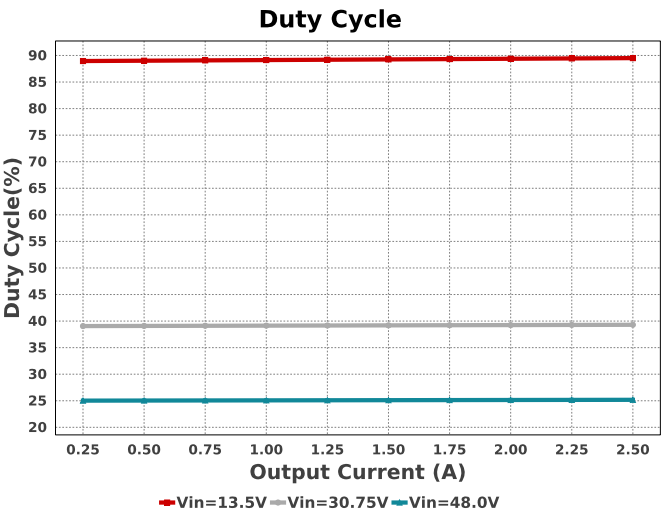
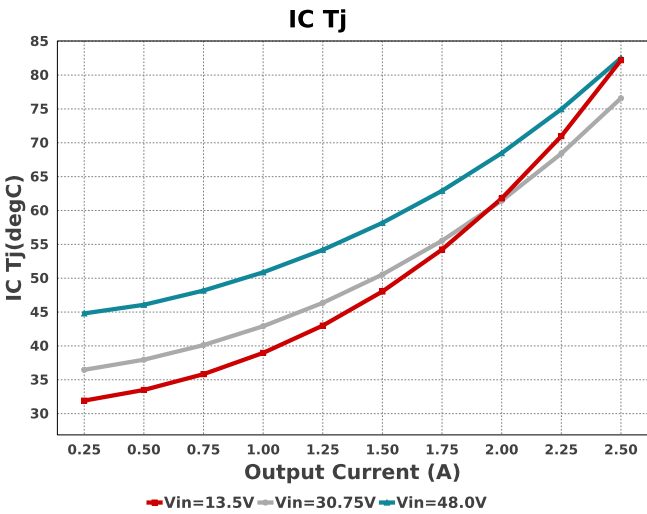
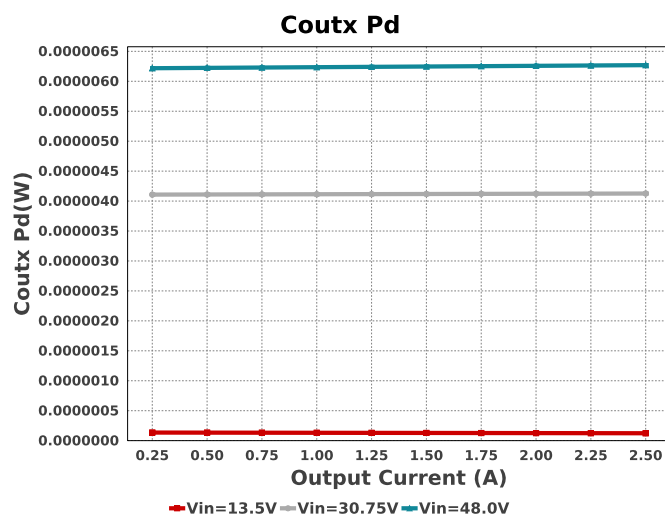
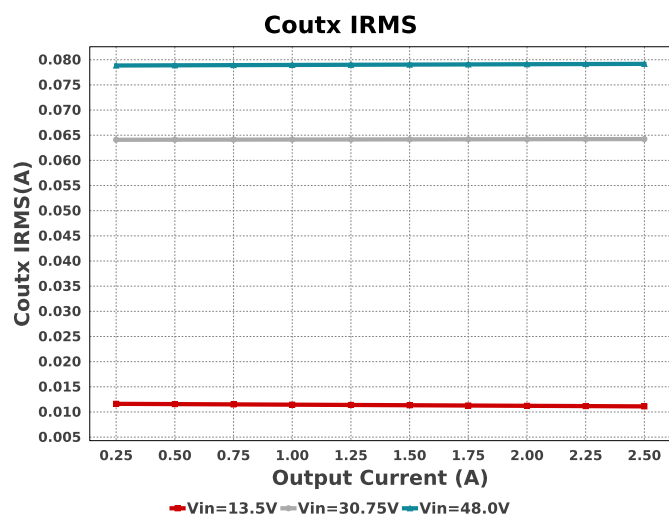
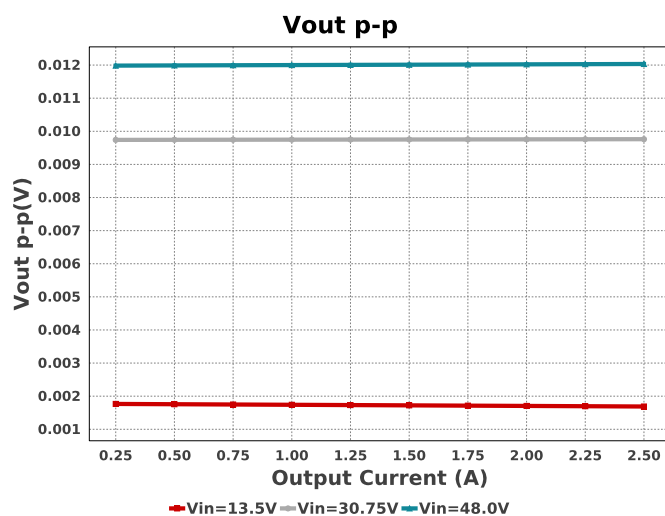
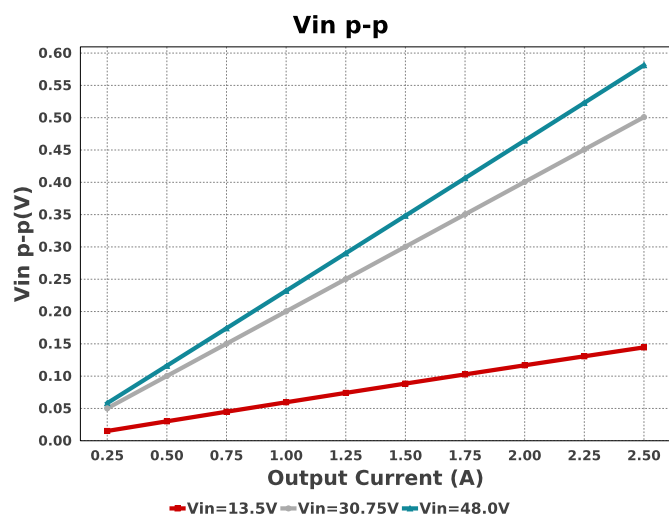
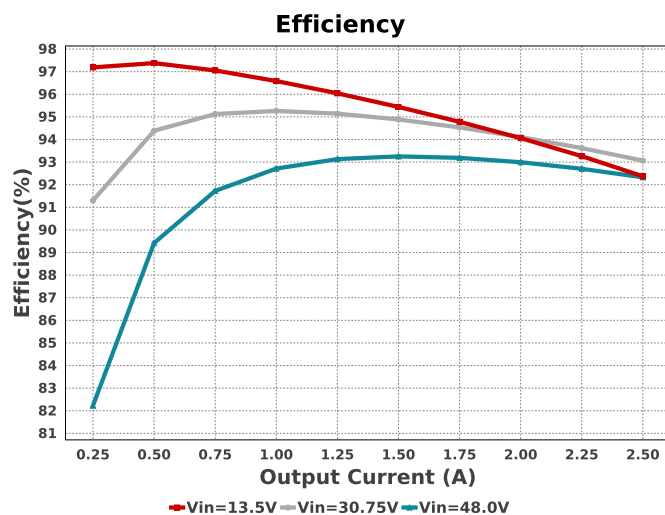
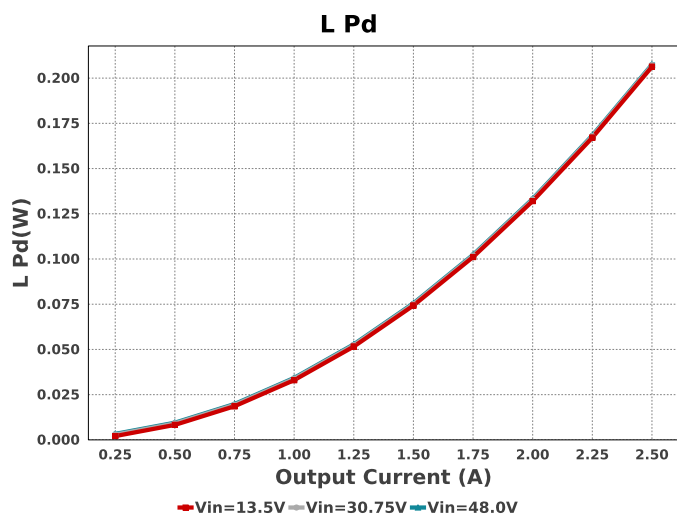


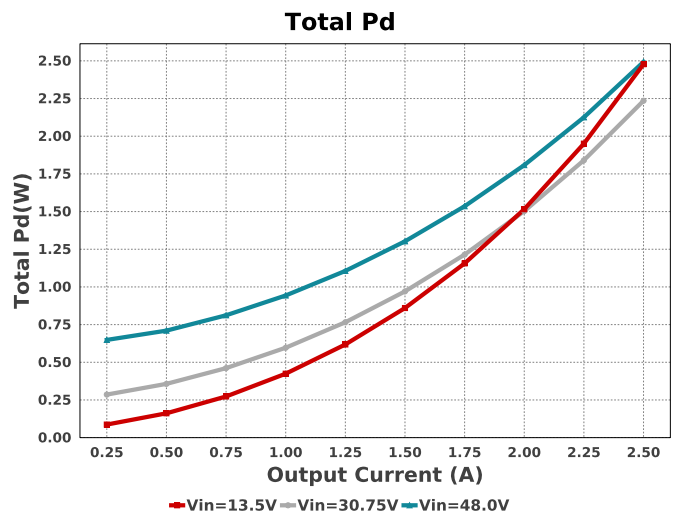
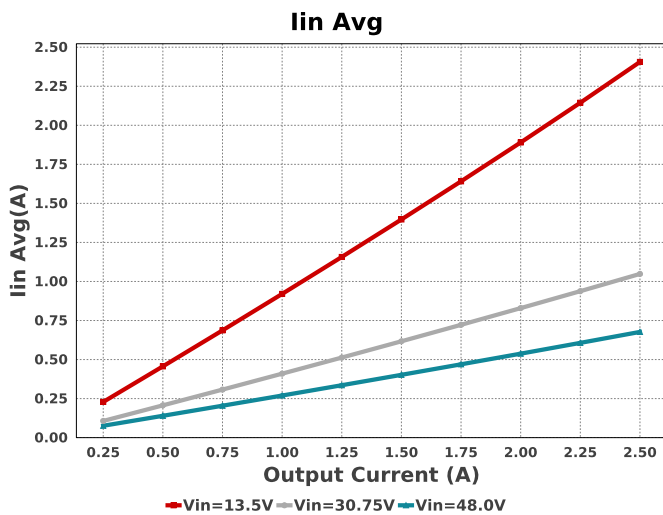
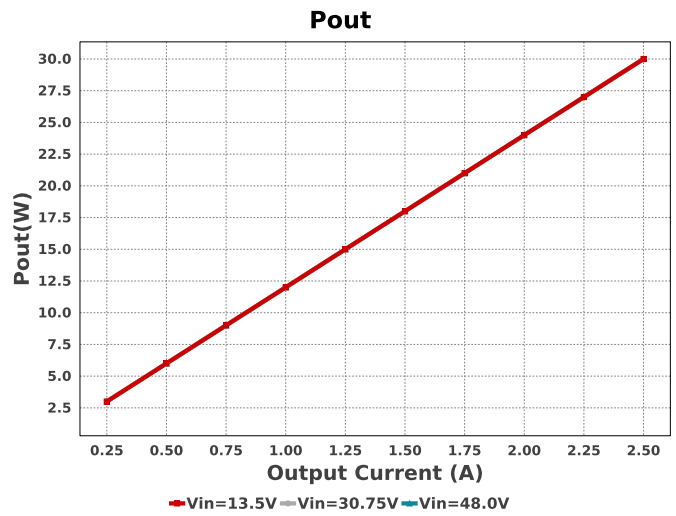
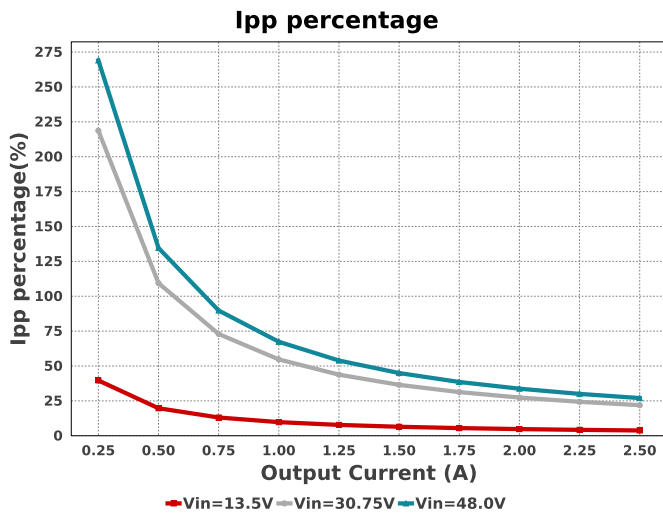
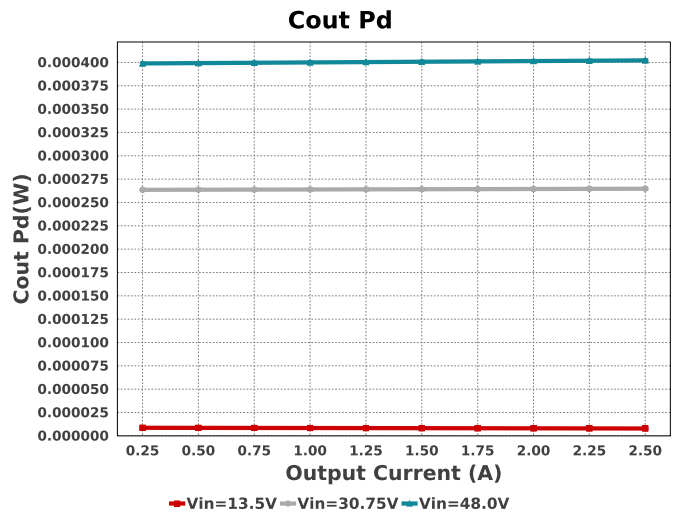
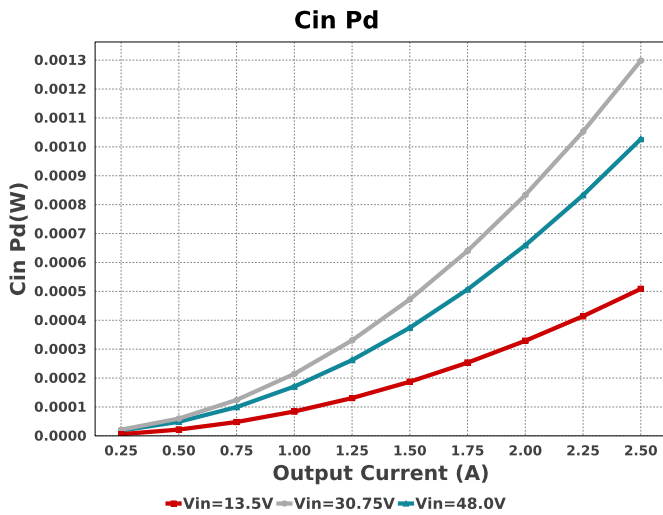


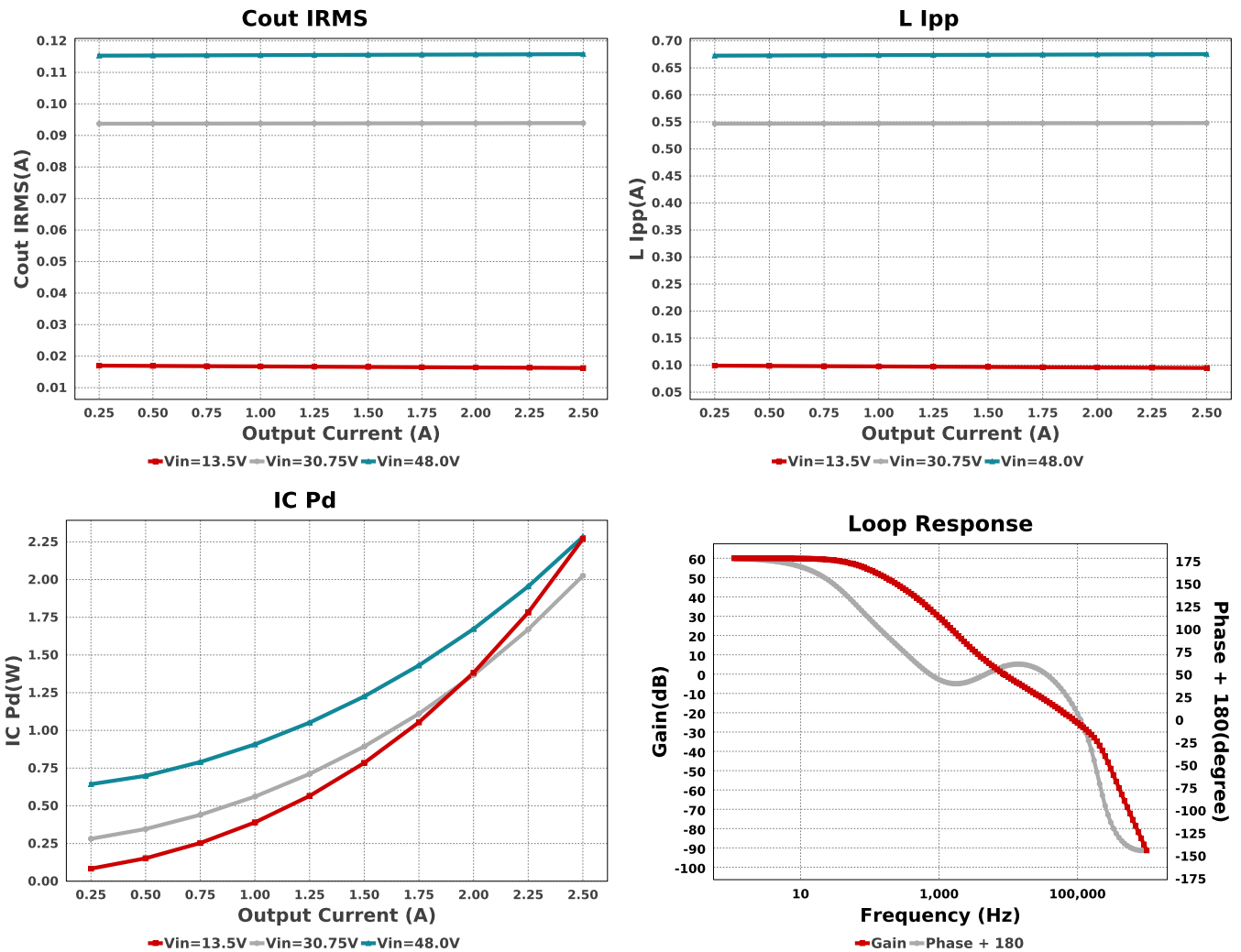
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Topology = Buck  
Created = 2025-06-01 18:33:04.256  
BOM Cost = \$3.87  
BOM Count = 13  
Total Pd = 2.49W

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Rfbb	Vishay-Dale	CRCW040210K0FKED Series= CRCW..e3	Res= 10.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm <sup>2</sup>
Rfbt	Vishay-Dale	CRCW0402110KFKED Series= CRCW..e3	Res= 110.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm <sup>2</sup>
Rpgood	Vishay-Dale	CRCW060310K0FKEA Series= CRCW..e3	Res= 10.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	0603 5 mm <sup>2</sup>
Rt	Vishay-Dale	CRCW060364K9FKEA Series= CRCW..e3	Res= 64.9 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	0603 5 mm <sup>2</sup>
U1	Texas Instruments	LMR38025SQDRRRQ1	Switcher	1	\$1.35	DRR0012E 16 mm <sup>2</sup>









## Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	1.089 A	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	1.027 mW	Capacitor	Input capacitor power dissipation
3.	Cout IRMS	115.787 mA	Capacitor	Output capacitor RMS ripple current
4.	Cout Pd	402.2 $\mu$ W	Capacitor	Output capacitor power dissipation
5.	Coutx IRMS	79.179 mA	Capacitor	Output capacitor_x RMS ripple current
6.	Coutx Pd	6.269 $\mu$ W	Capacitor	Output capacitor_x power loss
7.	IC Ipk	2.838 A	IC	Peak switch current in IC
8.	IC Pd	2.283 W	IC	IC power dissipation
9.	IC Tj	82.507 degC	IC	IC junction temperature
10.	IC Tolerance	5.0 mV	IC	IC Feedback Tolerance
11.	ICThetaJA Effective	23.0 degC/W	IC	Effective IC Junction-to-Ambient Thermal Resistance
12.	Iin Avg	676.94 mA	IC	Average input current
13.	Ipp percentage	27.015 %	Inductor	Inductor ripple current percentage (with respect to average inductor current)
14.	L Ipp	675.38 mA	Inductor	Peak-to-peak inductor ripple current
15.	L Pd	207.5 mW	Inductor	Inductor power dissipation
16.	Cin Pd	1.027 mW	Power	Input capacitor power dissipation
17.	Cout Pd	402.2 $\mu$ W	Power	Output capacitor power dissipation
18.	Coutx Pd	6.269 $\mu$ W	Power	Output capacitor_x power loss
19.	IC Pd	2.283 W	Power	IC power dissipation
20.	L Pd	207.5 mW	Power	Inductor power dissipation
21.	Total Pd	2.493 W	Power	Total Power Dissipation
22.	BOM Count	13	System Information	Total Design BOM count
23.	Cross Freq	8.7 kHz	System Information	Bode plot crossover frequency
24.	Duty Cycle	25.179 %	System Information	Duty cycle
25.	Efficiency	92.327 %	System Information	Steady state efficiency
26.	FootPrint	394.0 mm <sup>2</sup>	System Information	Total Foot Print Area of BOM components

#	Name	Value	Category	Description
27.	Frequency	405.764 kHz	System Information	Switching frequency
28.	Gain Marg	-26.628 dB	System Information	Bode Plot Gain Margin
29.	Inductor ripple current requirement used for Inductor selection	40.0 %	System Information	Custom Inductor ripple current (% of average inductor current) requirement used for Inductor selection
30.	Iout	2.5 A	System Information	Iout operating point
31.	Iout transient step used for Cout calculations	1.25 A	System Information	Custom Transient current step requirement that was used for Cout selection (A).
32.	Low Freq Gain	59.985 dB	System Information	Gain at 1Hz
33.	Mode	FCCM	System Information	Conduction Mode
34.	Overshoot Value	33.202 mV	System Information	Theoretical Vout Overshoot Value
35.	Phase Marg	59.595 deg	System Information	Bode Plot Phase Margin
36.	Pout	30.0 W	System Information	Total output power
37.	Total BOM	\$3.87	System Information	Total BOM Cost
38.	Undershoot Value	46.773 mV	System Information	Theoretical Vout Undershoot Value
39.	Vin	48.0 V	System Information	Vin operating point
40.	Vin p-p	581.32 mV	System Information	Peak-to-peak input voltage
41.	Vout	12.0 V	System Information	Operational Output Voltage
42.	Vout Actual	12.0 V	System Information	Vout Actual calculated based on selected voltage divider resistors
43.	Vout Ripple requirement used for Cout calculations	500.0 m%	System Information	Custom maximum output ripple requirement that was used for Cout selection(% of Vout).
44.	Vout Tolerance	2.361 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
45.	Vout p-p	12.033 mV	System Information	Peak-to-peak output ripple voltage
46.	Vout transient requirement used for Cout calculations	3.0 %	System Information	Custom Transient voltage change requirement that was used for Cout selection (% of Vout).

## Design Inputs

Name	Value	Description
Iout	2.5	Maximum Output Current
VinMax	48.0	Maximum input voltage
VinMin	13.5	Minimum input voltage
Vout	12.0	Output Voltage
base_pn	LMR38025-Q1	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature
UserFsw	400.0 k	Customer Selected Frequency

## WEBENCH® Assembly

### Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of  $C_{in}$  and  $C_{out}$ , and the inductance and DC resistance of  $L_1$  before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

### Soldering Component to Board

If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab down to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

### Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 13.5V and set the input supply's current limit to zero. With the input supply off connect up the input supply to  $V_{in}$  and GND. Connect a digital volt meter and a load if needed to set the minimum load of the design from  $V_{out}$  and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

### Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between  $V_{in}$  and GND, a load is connected between  $V_{out}$  and GND and a current meter is connected in series between  $V_{out}$  and the load. The load must be able to handle at least rated output power + 50% ( 7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



### Design Assistance

1. Master key : 3A09369785B968091A003B956300BD89[v1]
2. **LMR38025-Q1** Product Folder : <http://www.ti.com/product/LMR38025%2DQ1> : contains the data sheet and other resources.

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